BAP51-03

Silicon PIN diode

Rev. 5.1 — 8 February 2019 Product data sheet

1 Product profile

1.1 General description

General-purpose pin diode in an SOD323 small plastic SMD package.

1.2 Features and benefits

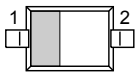
- Low diode capacitance: maximum 1.05 pF
- Low diode forward resistance: max. 0.7 Ω
- AEC-Q101 qualified

1.3 Applications

- General RF applications

2 Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode	 Top view	 sym006
2	anode		

3 Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP51-03	-	plastic surface-mounted package; 2 leads	SOD323

4 Marking

Table 3. Marking code

Type number	Marking code
BAP51-03	A5[1]

[1] The marking bar indicates the cathode (see simplified outline graphic in Table 1).

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	continuous reverse voltage		-	50	V
I_F	continuous forward current		-	50	mA
P_{tot}	total power dissipation	$T_{sp} \leq 90$ °C	-	500	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		120	K/W

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7 Characteristics

Table 6. Characteristics

T_j = 25 °C unless otherwise specified.

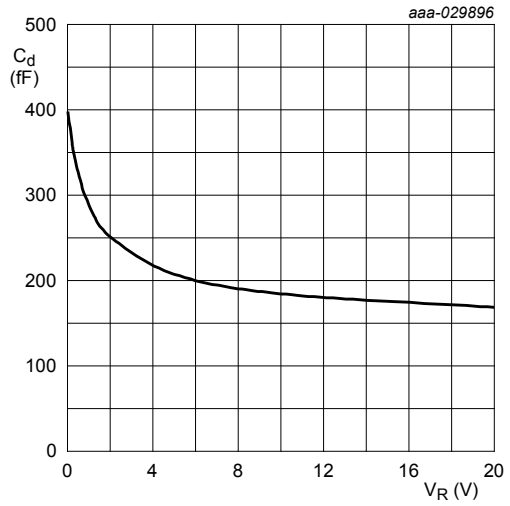
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	I_F = 50 mA	-	0.95	1.1	V
V_R	reverse voltage	I_R = 10 µA	50	-	-	V
I_R	reverse current	V_R = 50 V	-	-	100	nA
C_d	diode capacitance	f = 1 MHz (see Figure 1)				
		V_R = 0 V	-	0.4	-	pF
		V_R = 1 V	-	0.3	0.55	pF
		V_R = 5 V	-	0.2	0.35	pF
r_D	diode forward resistance	f = 100 MHz (see Figure 2)				
		I_F = 0.5 mA [1]	-	5.5	9	Ω
		I_F = 1 mA [1]	-	3.6	6.5	Ω
		I_F = 10 mA [1]	-	1.5	2.5	Ω
τ_L	charge carrier life time	when switched from I_F = 10 mA to I_R = 6 mA; R_L = 100 Ω; measured at I_R = 3 mA	-	550	-	ns

[1] Guaranteed on AQL basis; inspection level S4, AQL 1.0

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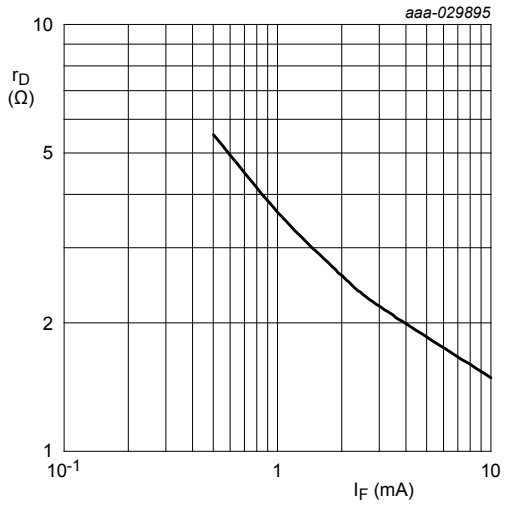
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8 Graphical data



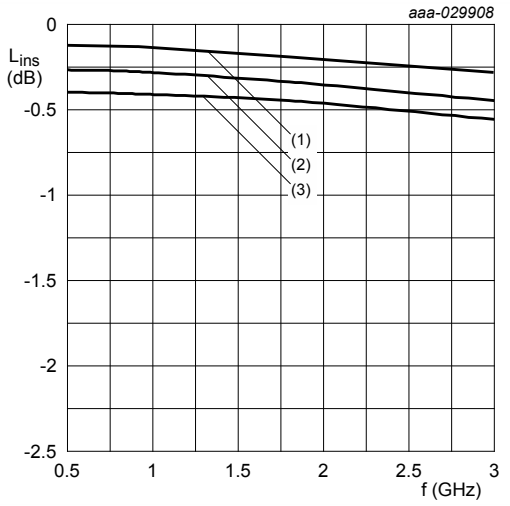
T_j = 25 °C; f = 1 MHz

Figure 1. Diode capacitance as a function of reverse voltage (typical values)



T_j = 25 °C; f = 100 MHz.

Figure 2. Diode forward resistance as a function of forward current (typical values)



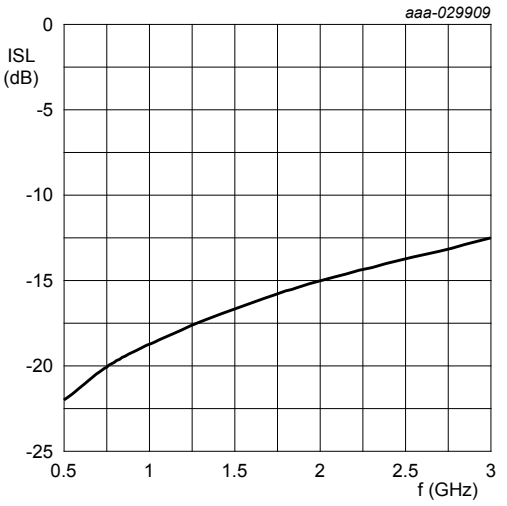
Diode inserted in series with a 50 Ω strip line circuit and biased via the analyzer T-network; T_{amb} = 25 °C

(1) I_F = 10 mA

(2) I_F = 1 mA

(3) I_F = 0.5 mA

Figure 3. Insertion loss of the diode as a function of frequency (typical values)



Diode zero-biased and inserted in series with a 50 Ω strip line circuit and biased via the analyzer T-network; T_{amb} = 25 °C; f = 100 MHz

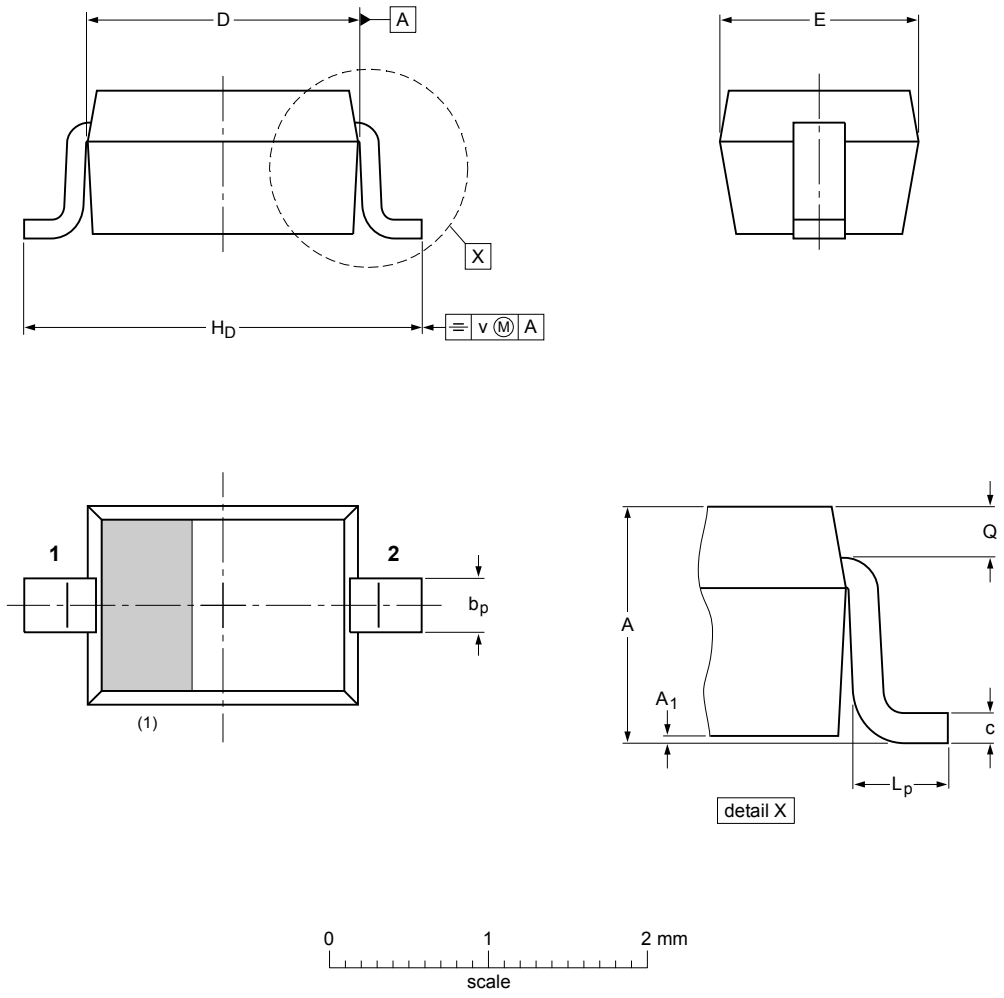
Figure 4. Isolation of the diode as a function of frequency (typical values)

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9 Package outline

Plastic surface-mounted package; 2 leads **SOD323**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	c	D	E	H_D	L_p	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD323			SC-76			~~03-12-17~~ 06-03-16

Figure 5. Package outline SOD323

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10 Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP51-03 v.5.1	20190208	Product data sheet	-	BAP51-03 v.5
Modifications:	• aligned the title of the data sheet with the description on the Internet			
BAP51-03 v.5	20181126	Product data sheet	-	BAP51-03 v.3.1
Modifications:	• AEC-Q101 qualification added to the features and benefits • Section 1.2 "Features and benefits" has been updated. • The "Legal information" pages have been updated to automotive version			
BAP51-03 v.4.1	20040211	Product data sheet	-	-

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11 Legal information

11.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
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